

曜凌光電股份有限公司

 住址: 42878 台中市大雅区科雅路 25 號 5F
 WEB: <u>http://www.Raystar-Optronics.com</u>

 5F., No.25, Keya Rd., Daya Dist., Taichung
 E-mail: sales@raystar-optronics.com

 City 428, Taiwan
 Tel:886-4-2565-0761

RG12864C-TIW-V

SPECIFICATION

CUSTOMER:

APPROVED BY

PCB VERSION

DATE

FOR CUSTOMER USE ONLY

SALES BY	APPROVED BY	CHECKED BY	PREPARED BY

ISSUED DATE:



Contents

		Page
1.	Revision History	3
2.	General Specification	4
3.	Module Coding System	5
4.	Interface Pin Function	6
5.	Outline dimension & Block Diagram	7
6.	Display Control Instruction	8
7.	Detailed Explanation	9
8.	Timing Characteristics	11
9.	Optical Characteristics	12
10.	Absolute Maximum Ratings	13
11.	Electrical Characteristics	13
12.	Backlight Information	14
13.	Reliability	15
14.	Inspection specification	16
15.	Precautions in use of LCD Modules	20
16	Material List of Components for RoHs	21
17.	Recommendable storage	21



1. Revision History

DATE	VERSION	REVISED PAGE NO.	Note
2012/06/15	1		First issue



2. General Specification

The Features is described as follow:

- Module dimension: 78 x 70.0 x 14.3 (max.) mm³
- View area:62.0 x 44.0 mm²
- Active area: 56.3 x 38.38 mm²
- Number of dots: 128 x 64
- Dot size: 0.42 x 0.58 mm²
- Dot pitch: 0.44 x 0.60 mm²
- LCD type: FSTN Negative Transmissive,
- Duty: 1/64
- View direction: 6 o'clock
- Backlight Type: LED White



3. Module Coding System

R	G	12864	С	-	Т	I	W	-	V
1	2	3	4	-	5	6	7	-	8

Item		Description	on
1	R : Raystar O	ptronics Inc.	
2	Display	C: Character Type,	
2		G : Graphic Type	
3		s : 128 x64 Dots	
4	Serials code		
		P : TN Positive, Gray	
		N : TN Negative,	
		G : STN Positive, Gray	A the second
5	LCD	Y: STN Positive, Yellow Gr	een
		B : STN Negative, Blue	
		F : FSTN Positive	
		T : FSTN Negative	
		A : Reflective, N.T, 6:00	K : Transflective, W.T,12:00
	Polarizer	D : Reflective, N.T, 12:00	1 : Transflective, U.T,6:00
	Type,	G: Reflective, W. T, 6:00	4 : Transflective, U.T.12:00
		J: Reflective, W. T, 12:00	C: Transmissive, N.T,6:00
6	Temperature	0 : Reflective, U. T, 6:00	F: Transmissive, N.T,12:00
	range,	3 : Reflective, U. T, 12:00	I : Transmissive, W. T, 6:00
	View	B: Transflective, N.T,6:00	L: Transmissive, W.T,12:00
	direction	E: Transflective, N.T.12:00	2 : Transmissive, U. T, 6:00
		H: Transflective, W.T,6:00	5 : Transmissive, U.T,12:00
		N : Without backlight	Y: LED, Yellow Green
		P : EL, Blue green	A : LED, Amber
7	Backlight	T : EL, Green	W : LED, White
		D : EL, White	O: LED, Orange
		F : CCFL, White	G : LED, Green
8	Special code	V: Build-in Negative Voltage	

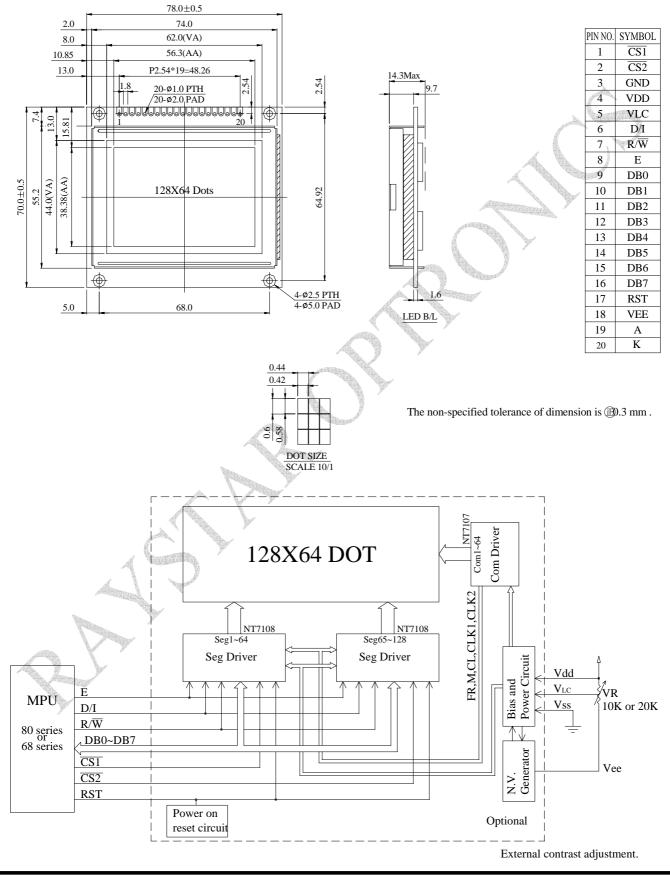


4. Interface Pin Function

Pin No.	Symbol	Level	Description
1	CS1	L	Select Segment 1 ~ Segment 64
2	CS2	L	Select Segment 65 ~ Segment 128
3	GND	0V	Ground
4	Vdd	5.0V	Supply voltage for logic
5	V _{LC}	(Variable)	Operating voltage for LCD
6	D/I	H/L	H: Data , L: Instruction
7	R/W	H/L	H: Read(MPU←Module) , L :Write(MPU→Module)
8	E	Н	Enable signal
9	DB0	H/L	Data bus line
10	DB1	H/L	Data bus line
11	DB2	H/L	Data bus line
12	DB3	H/L	Data bus line
13	DB4	H/L	Data bus line
14	DB5	H/E	Data bus line
15	DB6	H/L	Data bus line
16	DB7	HIL	Data bus line
17	RST	J ^{ar}	Reset the LCM
18	VEE		Negative voltage output (Built-in)
19	A		Power supply for LED B/L+
20	К		Power supply for LED B/L-



5. Outline Dimension & Block Diagram





6. Display Control Instruction

The display control instructions control the internal state of the NT7108. Instruction is received from MPU to NT7108 for the display control. The following table shows various instructions.

Instruction	RS	R/W	DB7	DB6	DB5	DB4	DB3	DB2	DB1	DB0	Function	1
Display on/off	L	L	L	L	н	н	н	н	н	L/H	Controls the display on or off. Internal status and display RAM data is not affected. L:OFF, H:ON	
Set address (Y address)	L	L	L	Н		Y	addre	ss (0-6	63)	•	Sets the Y address in the Y address counter.	p anorralization
Set page (X address)	L	L	н	L	н	Н	Н	Pa	age (O	-7)	Sets the X address at the X address register.	
Display Start line (Z address)	L	L	н	Н	Display start line (0-63)				(0-63)		Indicates the display data RAM displayed at the top of the screen.	
Status read	L	н	Busy	L	On/ Off	Reset	L	L	L	L	Read status. BUSY L: Ready H: In operation ON/OFF L: Display ON H: Display OFF RESET L: Normal H: Reset	
Write display data	н	L			-	Write data					Writes data (DB0: 7) into display data RAM. After writing instruction, Y address is increased by 1 automatically.	
Read display data	Н	Н				Read	l data				Reads data (DB0: 7) from display data RAM to the data bus.]

H C H



7. Detailed Explanation

[RS	R/W	DB7	DB6	DB5	DB4	DB3	DB2	DB1	DB0
	0	0	0	0	1	1	1	1	1	D

The display data appears when D is 1 and disappears when D is 0. Though the data is not

<u>on the</u>

screen with D=0, it remains in the display data RAM. Therefore, you can make it appear by changing D=0 into D=1.

SET ADDRESS (Y ADDRESS)

						5 0.25VGA	80		
RS	R/W	DB7	DB6	DB5	DB4	DB3	DB2	DB1	DB0
0	0	0	1	AC5	AC4	AC3	AC2	AC1	AC0

Y address (AC0-AC5) of the display data RAM is set in the Y address counter. An address is set by

instruction and increased by 1 automatically by read or write operations of display data.

SET PAGE (X ADDRESS)

RS	R/W	DB7	DB6	DB5	DB4	DB3	DB2	DB1	DB0
0	0	1	0	1	1	1	AC2	AC1	AC0

X address (AC0-AC2) of the display data RAM is set in the X address register. Writing or reading to

or from MPU is executed in this specified page until the next page is set.

DISPLAY START LINE (Z ADDRESS)

RS	R/W	DB7	DB6	DB5	DB4	DB3	DB2	DB1	DB0
0	0	1	1	AC5	AC4	AC3	AC2	AC1	AC0

Z address (AC0-AC5) of the display data RAM is set in the display start line register and displayed

at the top of the screen. When the display duty cycle is 1/64 or others (1/32-1/64), the data of total

line number of LCD screen, from the line specified by display start line instruction, is displayed.



STATUS READ

RS	R/W	DB7	DB6	DB5	DB4	DB3	DB2	DB1	DB0
0	1	BUSY	0	ON/OFF	RESET	0	0	0	0

• BUSY

When BUSY is 1, the Chip is executing internal operation and no instructions are accepted. When BUSY is 0, the Chip is ready to accept any instructions.

• ON/OFF

When ON/OFF is 1, the display is OFF.

When ON/OFF is 0, the display is ON.

• RESET

When RESET is 1, the system is being initialized.

In this condition, no instructions except status read can be accepted.

When RESET is 0, initializing has finished and the system is in usual operation condition.

WRITE DISPLAY DATA

							active actives			
[RS	R/W	DB7	DB6	DB5	DB4	DB3	DB2	DB1	DB0
[1	0	D7	D6	D5	D4	D3	D2	D1	D0

Writes data (D0-D7) into the display data RAM. After writing instruction, Y address is increased by

1automatically.

READ DISPLAY DATA

RS	R/W	DB7	DB6	DB5	DB4	DB3	DB2	DB1	DB0
1	1	D7	D6	D5	D4	D3	D2	D1	D0

Reads data (D0-D7) from the display data RAM. After reading instruction, Y address is increased by

1 automatically.

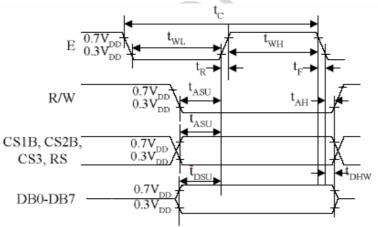


8. Timing Characteristics

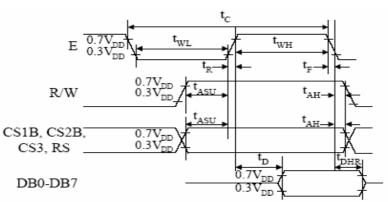
MPU Interface

(T=25°C, VDD=+5.0V±0.5)

			•		
Characteristic	Symbol	Min	Туре	Max	Unit
E cycle	tcyc	1000	_	_	ns
E high level width	twh E	450	_	_	ns
E low level width	tw IE	450	_	_	ns
E rise time	tr	_	_	25	ns
E tall time	tf	_	_	25	ns
Address set-up time	tas	140			ns
Address hold time	tah	10	_	\rightarrow	ns
Data set-up time	tdsw	200			ns
Data delay time	tddr	_		320	ns
Data hold time (write)	tdhw	10		_	ns
Data hold time (read)	tdhr	20			ns



MPU Write Timing



MPU Read Timing



9. Optical Characteristics

ITEM	SYMBAL	CONDITION	MIN	TYP	MAX	UNIT		
	(V)θ	CR≧2	30		60	deg.		
View Angle	(Н)ф	CR≧2	-45	_	45	deg.		
Contrast Ratio	CR	_	_	5	_			
	T rise	_	_	200	300	ms		
Response Time	T fall	_	_	150 🔎	200	ms		
Definitions View Angles			Contrast	Ratio				
7 (Vi	sual angle direction)	Bri	ahtness at se	lactad stata (BS)		
			$CR = \frac{Brightness at selected state (BS)}{Brightness at non-selected state (Bns)}$					
		Se	elected state	-	in beleeted st			
Y _θ	Χφ	Brightness (%)	Bns	Non-selected Bs	_ or LCD drivin	זס		
0			operati	ng voluge it		-6		
Response time	e							
Nonselected Condition	on S	Selected Condition		Nonsele	ected Condit	ion		
	·			— п		_		
						_		
						-		
Brightness		10 %			\square	90 %		
	tr Rise Time			Decay	td Fime (fall ti	me tf)		

3 Pages



10. Absolute Maximum Ratings

ITEM	SYMBOL	MIN.	TYP.	MAX.	UNIT
Operating Temperature	T _{OP}	-20	_	+70	°C
Storage Temperature	T _{ST}	-30	_	+80	°C
Input Voltage	VI	0	_	V _{DD}	v Ċ
Supply Voltage For Logic	V _{DD-} V _{SS}	0	_	6.5	V
Supply Voltage For LCD	V _{DD} -V _{LCD}	0	_	17.0	v

11. Electrical Characteristics

			· · · · · · · · · · · · · · · ·	and a second sec		
ITEM	SYMBOL	CONDITION	MIN.	TYP.	MAX.	UNIT
Logic Voltage	V_{DD} - V_{SS}		4.5	5.0	5.5	V
		Ta=-20℃		_	_	V
Supply Voltage For	V _{DD} -V _{LCD}	Ta=25 ℃	8.2	8.5	8.8	V
LCD		Ta=+70 ℃	_	_	_	V
Input High Volt.	VIII		2.0	_	V _{DD}	V
Input Low Volt.	VIL	_	0	_	0.8	V
Output High Volt.	Voh		2.4	_	V _{DD}	V
Output Low Volt.	V _{OL}		0	_	0.4	V
Supply Current	I _{OP}	_	2.0	2.5	4.0	mA
	•		•	•	•	



12. Backlight Information

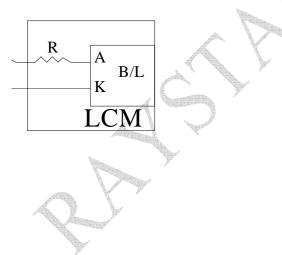
Specification

PARAMETER	SYMBOL	MIN	ТҮР	MAX	UNIT	TEST	CONDITION
Supply Current	I _{LED}	—	64	80	mA	V=3.5V	(Alexandre
Supply Voltage	V	3.4	3.5	3.6	V	—	A
Reverse Voltage	VR	_	_	5	V	_	
Luminous Intensity	IV	460	580	_	cd/m²	I _{LED} =641	mA
Life Time	_		50K	_	hr.	I _{LED} ≦64	mA
Color	White						

Note:

The LED of B/L is drive by current only; drive voltage is for reference only. Drive voltage has to make driving current under safety area (current between minimum and maximum).

.Drive from pin19,pin20





13. Reliability

Content of Reliability Test (wide temperature, -20°c~70°C)

	Environmental Test		
Test Item	Content of Test	Condition	Note
High Temperature storage	Endurance test applying the high storage temperature for a long time.	80℃ 200hrs	2
Low Temperature storage	Endurance test applying the high storage temperature for a long time.	-30℃ 200hrs	1,2
High Temperature Operation	Endurance test applying the electric stress (Voltage & Current) and the thermal stress to the element for a long time.	70℃ 200hrs	-
Low Temperature Operation	Endurance test applying the electric stress under low temperature for a long time.	-20°C 200hrs	1
High Temperature/ Humidity Operation	The module should be allowed to stand at 60°C,90%RH max For 96hrs under no-load condition excluding the polarizer, Then taking it out and drying it at normal temperature.	60°C ,90%RH 96hrs	1,2
Thermal shock resistance	The sample should be allowed stand the following 10 cycles of operation	-20℃ /70℃ 10 cycles	-
Vibration test	Endurance test applying the vibration during transportation and using.	fixed amplitude: 15mm Vibration. Frequency: 10~55Hz. One cycle 60 seconds to 3 directions of X,Y,Z for Each 15 minutes	3
Static electricity test	Endurance test applying the electric stress to the terminal.	VS=800V,RS= 1.5kΩ CS=100pF 1 time	

Note1: No dew condensation to be observed.

Note2: The function test shall be conducted after 4 hours storage at the normal temperature and humidity after remove from the test chamber.

Note3: Vibration test will be conducted to the product itself without putting it in a container.

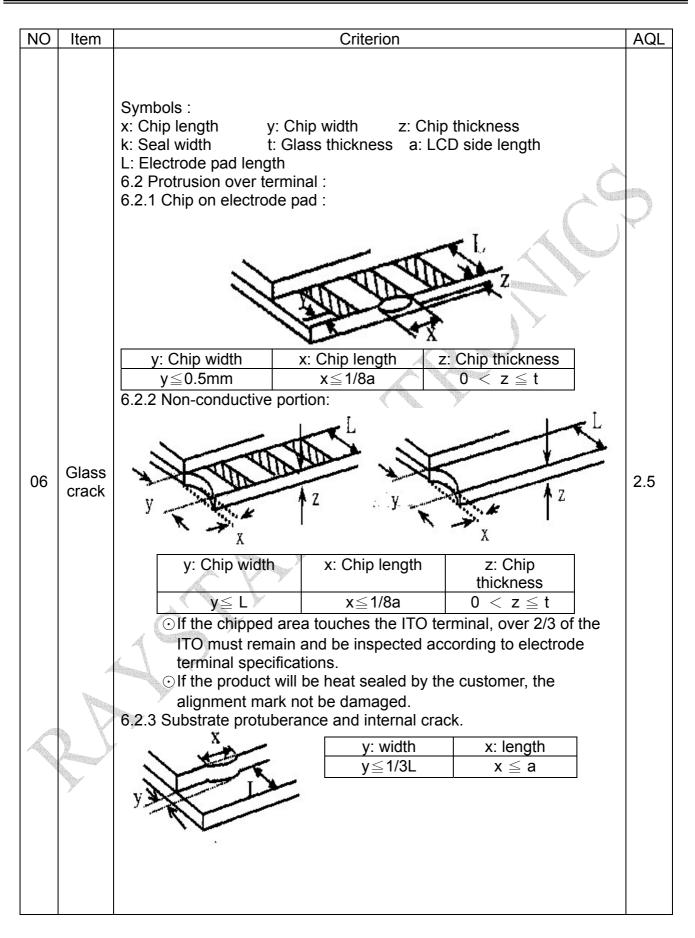


14. Inspection specification

NO	Item			Criterion		AQL		
01	Electrical Testing	defect. 1.2 Missing cha 1.3 Display mal 1.4 No function	racter, do function. or no dis sumption g angle de uct types.	play. exceeds product		0.65		
02	Black or white spots on LCD (display only)	than three w 2.2 Densely spa 3mm	 White and black spots on display ≤0.25mm, no more than three white or black spots present. Densely spaced: No more than two spots or lines within 3mm 					
03	LCD black spots, white spots, contaminatio	3.1 Round type : As following drawing $\Phi=(x+y)/2$						
	n (non-display)	3.2 Line type : ((As follow Length	Width	Acceptable Q TY			
				W≦0.02	Accept no dense	2.5		
	A	and the second se	L≦3.0 L≦2.5	$\begin{array}{c} 0.02\!<\!W\!\leq\!0.03\\ 0.03\!<\!W\!\leq\!0.05 \end{array}$	2			
	V Y			0.05 <w< td=""><td>As round type</td><td></td></w<>	As round type			
\mathbb{R}	-	If bubbles are v judge using bla	ck spot	Size Φ	Acceptable Q TY			
	Polarizer	specifications, i easy to find, mu		Ф≦0.20	Accept no dense	0.5		
04	bubbles	check in specify		$0.20 < \Phi \leq 0.50$	3	2.5		
		direction.		$0.50 < \Phi \le 1.00$	2			
				1.00<Φ	0			
				Total Q TY	3			

NO	Itom		Critorion		
NO 05	Item Scratches	Follow NO.3 LCD bla	Criterion	contamination	AQL
03	Scialcines	Symbols Define: x: Chip length y	r: Chip width z: C : Glass thickness a: th: p :	Chip thickness LCD side length	
			y: Chip width Not over viewing area	x: Chip length x≦1/8a	
		1/2t <z≦2t< td=""><td>Not exceed 1/3k</td><td>x≦1/8a</td><td></td></z≦2t<>	Not exceed 1/3k	x≦1/8a	
		\odot If there are 2 or mo	re chips, x is total leng		
06	Chipped glass	6.1.2 Corner crack:	17	v	2.5
			X	,	
		z: Chip thickness	y: Chip width	x: Chip length	
	A	Z≦1/2t	Not over viewing area	x≦1/8a	
		$1/2t < z \le 2t$	Not exceed 1/3k	x≦1/8a	
		⊙If there are 2 or mo	re chips, x is the total	length of each chip.	







NO	Item	Criterion	AQL
07	Cracked glass	The LCD with extensive crack is not acceptable.	2.5
08	Backlight elements	 8.1 Illumination source flickers when lit. 8.2 Spots or scratched that appear when lit must be judged. Using LCD spot, lines and contamination standards. 8.3 Backlight doesn't light or color wrong. 	0.65 2.5 0.65
09	Bezel	9.1 Bezel may not have rust, be deformed or have fingerprints, stains or other contamination.9.2 Bezel must comply with job specifications.	2.5 0.65
10	PCB · COB	 10.1 COB seal may not have pinholes larger than 0.2mm or contamination. 10.2 COB seal surface may not have pinholes through to the IC. 10.3 The height of the COB should not exceed the height indicated in the assembly diagram. 10.4 There may not be more than 2mm of sealant outside the seal area on the PCB. And there should be no more than three places. 10.5 No oxidation or contamination PCB terminals. 10.6 Parts on PCB must be the same as on the production characteristic chart. There should be no wrong parts, missing parts or excess parts. 10.7 The jumper on the PCB should conform to the product characteristic chart. 10.8 If solder gets on bezel tab pads, LED pad, zebra pad or screw hold pad, make sure it is smoothed down. 10.9 The Scraping testing standard for Copper Coating of PCB X * Y<=2mm² 	 2.5 2.5 0.65 2.5 0.65 0.65 2.5 2.5 2.5 2.5
11	Soldering	 11.1 No un-melted solder paste may be present on the PCB. 11.2 No cold solder joints, missing solder connections, oxidation or icicle. 11.3 No residue or solder balls on PCB. 11.4 No short circuits in components on PCB. 	2.5 2.5 2.5 0.65



NO	Item	Criterion	AQL
NO 12	Item General appearance	 12.1 No oxidation, contamination, curves or, bends on interface Pin (OLB) of TCP. 12.2 No cracks on interface pin (OLB) of TCP. 12.3 No contamination, solder residue or solder balls on product. 12.4 The IC on the TCP may not be damaged, circuits. 12.5 The uppermost edge of the protective strip on the interface pin must be present or look as if it causes the interface pin to sever. 12.6 The residual rosin or tin oil of soldering (component or chip component) is not burned into brown or black color. 12.7 Sealant on top of the ITO circuit has not hardened. 12.8 Pin type must match type in specification sheet. 12.9 LCD pin loose or missing pins. 12.10 Product packaging must the same as specified on 	AQL 2.5 0.65 2.5 2.5 2.5 2.5 2.5 0.65 0.65 0.65
		 packaging specification sheet. 12.11 Product dimension and structure must conform to product specification sheet. 	0.65

15. Precautions in use of LCD Modules

- 1. Avoid applying excessive shocks to the module or making any alterations or modifications to it.
- 2. Don't make extra holes on the printed circuit board, modify its shape or change the components of LCD module.
- 3. Don't disassemble the LCM.
- 4. Don't operate it above the absolute maximum rating.
- 5. Don't drop, bend or twist LCM.
- 6. Soldering: only to the I/O terminals.
- 7. Storage: please storage in anti-static electricity container and clean environment.
- 8. Raystar have the right to change the passive components

(Resistors, capacitors and other passive components will have different appearance and color caused by the different supplier.)

9. Raystar have the right to change the PCB Rev.





16. Material List of Components for RoHs

1. RAYSTAR Optronics Co., Ltd. hereby declares that all of or part of products, including, but not limited to, the LCM, accessories or packages, manufactured and/or delivered to your company (including your subsidiaries and affiliated company) directly or indirectly by our company (including our subsidiaries or affiliated companies) do not intentionally contain any of the substances listed in all applicable EU directives and regulations, including the following substances.

Exhibit A : The Harmful Material List

Material	(Cd)	(Pb)	(Hg)	(Cr6+)	PBBs	PBDEs	
Limited Value	100 ppm	1000 ppm	1000 ppm	1000 ppm	1000 ppm	1000 ppm	
Above limited value is set up according to RoHS							

- 2. Process for RoHS requirement :
 - (1) Use the Sn/Ag/Cu soldering surface; the surface of Pb-free solder is rougher than we used before.
 - (2) Heat-resistance temp. :

Reflow : 250° C, 30 seconds Max. ;

Connector soldering wave or hand soldering : 320° C, 10 seconds max.

(3) Temp. curve of reflow, max. Temp. : $235\pm5^{\circ}$ C ;

Recommended customer's soldering temp. of connector : 280° C, 3 seconds.

17. Recommendable storage

- 1. Place the panel or module in the temperature 25°C±5°C and the humidity below 65% RH
- 2. Do not place the module near organics solvents or corrosive gases.
- 3. Do not crush, shake, or jolt the module



		Page: 2
LCM	Sample E	Estimate Feedback Sheet
Module Number :		
1 • Panel Specification :		
1. Panel Type :	Pass	□ NG ,
2. View Direction :	Pass	□ NG ,
3. Numbers of Dots :	Pass	□ NG ,
4. View Area :	Pass	□ NG ,
5. Active Area :	Pass	□ NG ,
6.Operating	Pass	🗆 NG ,
Temperature :		
7.Storage Temperature :	Pass	□ NG ,
8.Others :		
2 · Mechanical Specification	<u>on</u> :	
1. PCB Size :	Pass	□ NG ,
2.Frame Size :	Pass	□ NG ,
3.Materal of Frame :	Pass	□ NG ,
4.Connector Position :	Pass	🗆 NG ,
5.Fix Hole Position :	Pass	🗆 NG ,
6.Backlight Position :	Pass	□ NG ,
7. Thickness of PCB :	Pass	🗆 NG ,
8. Height of Frame to	Pass	□ NG ,
PCB :		
9.Height of Module :	🗆 Pass 🔪	□ NG ,
10.Others :	Pass	🕫 NG ,
3 · <u>Relative Hole Size</u> :		
1.Pitch of Connector :	Pass	□ NG ,
2.Hole size of	Pass	□ NG ,
Connector :	J.	
3.Mounting Hole size	Pass	□ NG ,
4.Mounting Hole Type :	Pass	□ NG ,
5.Others	Pass	□ NG ,
4 · <u>Backlight Specification</u>		
1.B/L Type :	Pass	□ NG ,
2.B/L Color :	Pass	🗆 NG ,
		ED Type):□ Pass □ NG ,
4.B/L Driving Current :	Pass	□ NG ,
5.Brightness of B/L :	Pass	□ NG ,
6.B/L Solder Method :	Pass	□ NG ,
7.Others :	Pass	□ NG ,
		I

>> Go to page 2 <<



Page: 2

Module Number :			l ug
5 . Electronic Characteristic	s of Modu	le :	
1.Input Voltage :	Pass	□ NG ,	
2.Supply Current :	Pass	□ NG ,	
3.Driving Voltage for LCD :	Pass	□ NG ,	
4.Contrast for LCD :	Pass	□ NG ,	
5.B/L Driving Method :	Pass	□ NG ,	- A
6.Negative Voltage	Pass	□ NG ,	
Output :			
7.Interface Function :	Pass	□ NG ,	
8.LCD Uniformity :	Pass	□ NG ,	
9.ESD test :	Pass	□ NG ,	
10.Others :	Pass	□ NG ,	
6 <u>Summary</u> :		·	

Sales signature : _____ Customer Signature : _____

Date: / /